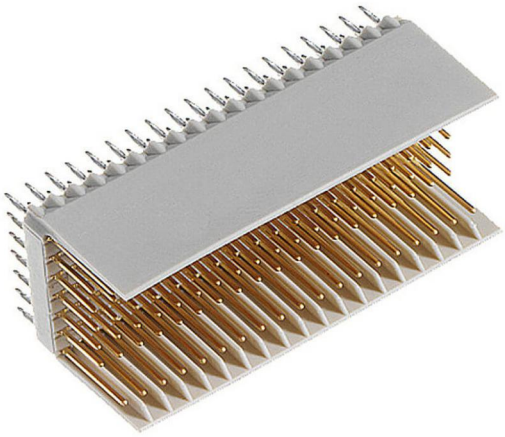
Product Data Sheet

hm2.0 Terminal Block, Type B19, Part No. 243-23320-15



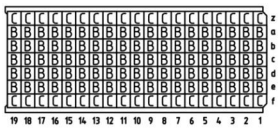


Illustration similar



Perpendicular



Press-fit

- Number of poles: 133
- Connector length: 3.7 mm
- for PCB thickness > 2.2 mm
- Tested in accordance with IEC 61076-4-101

» to product on www.ept.de

» to product group hm 2.0

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Product Data Sheet

hm2.0 Terminal Block, Type B19, Part No. 243-23320-15

Technical Specifications

Basics

Specification	IEC 61076-4-101
Performance Level	2
No. of Contacts	133
Termination Technology	Press-fit technology
Termination Length	3.7 mm
Operating Temperature Range	-55°C to +125°C

Material

Insulator Material	Glass-fiber-reinforced PBT, UL 94 V-0
CTI value *IEC 60112*	200
Contact Material	Bronze

Mechanical

Pitch	2.0 mm
Mating Force per Pin	Contact: max. 0.75 N, Shielding: max. 1 N
Separating Force per Pin	Contact: min. 0.15 N, Shielding: min. 0.15 N
Durability	> 250 insertion cycles

Electrical

Operational Current	1.5 A at +20°C, 1.0 A at +70°C
Contact Resistance	max. 20 mΩ
Clearance and Creepage	≥ 0.8 mm
Insulation Resistance	at least 10^4 MΩ
Test Voltage	750 V r.m.s.
Data Transfer Rate	3.125 Gbit/s

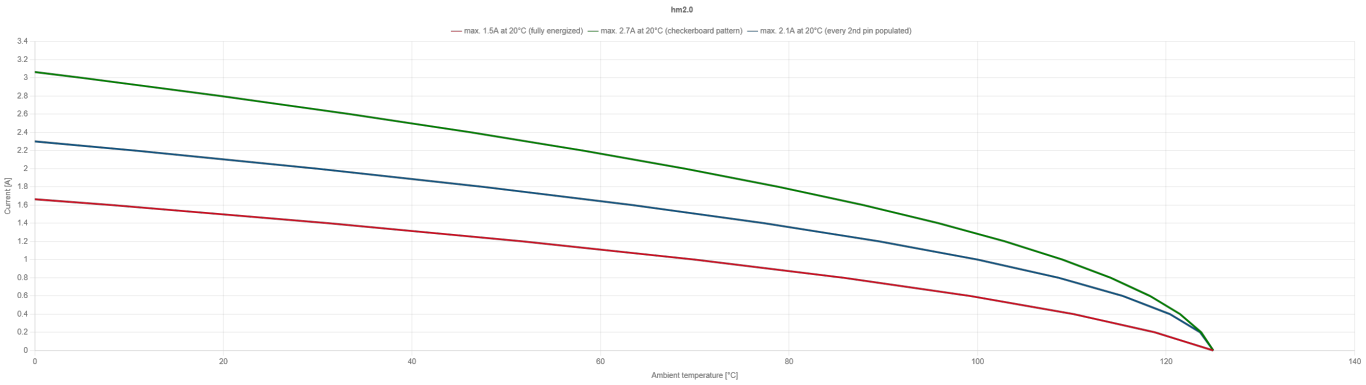
Approval / Compliance

UL file	E130314
Environment	RoHS compliant

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Derating Diagram

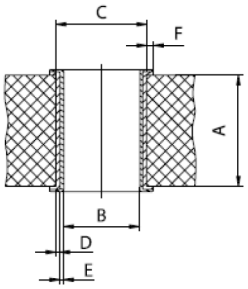


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Hole Specifications

Plated through-hole according to IEC 60352-5



Material	chem. Sn Schicht
Nennloch	**Ø 0.6 mm**
A Leiterplattendicke	min. 2.2 mm
B Endloch	Ø 0.60 ±0.05 mm
C Grundbohrung	0.70 ±0.02 mm
D Cu Schicht	min. 25 µm
E Oberfläche	max. 1.5 µm; chem. Sn Leiterplatten
F Restring	min. 0.1 mm

Material	Ni, Au Leiterplatten
Nennloch	**Ø 0.6 mm**
A Leiterplattendicke	min. 2.2 mm
B Endloch	Ø 0.60 ±0.05 mm
C Grundbohrung	0.70 ±0.02 mm
D Cu Schicht	min. 25 µm
E Oberfläche	Ni, Au Schicht, 0.05 - 0.2 µm Au über 2.5 - 5 µm Ni
F Restring	min. 0.1 mm

Material	rein Cu Leiterplatten
Nennloch	**Ø 0.6 mm**
A Leiterplattendicke	min. 2.2 mm
B Endloch	Ø 0.60 ±0.05 mm
C Grundbohrung	0.70 ±0.02 mm
D Cu Schicht	min. 25 µm
E Oberfläche	OSP*,z.B. GLICOAT-SMD (F2) mit 0.12 - 0.15 µm
F Restring	min. 0.1 mm

Material	HAL Sn Leiterplatten
Nennloch	**Ø 0.6 mm**
A Leiterplattendicke	min. 2.2 mm
B Endloch	Ø 0.60 ±0.05 mm
C Grundbohrung	0.70 ±0.02 mm
D Cu Schicht	min. 25 µm
E Oberfläche	HAL Sn, 5 - 15 µm
F Restring	min. 0.1 mm

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Modifications

Available on request

- Special configuration
- Other contact coatings

Drawings

Component data in 2D and 3D format you can download here:

» PDF » 3D IGES » 3D STEP » 3D PDF

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